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Launch of new Dry Etching equipment for optical devices

Oporun has developed a new type of Dry Etching equipment that enables sophisticated etching technology and mitigates environmental burden at the same time.

The etching technology is capable of microfabrication by patterning metal films and insulating films for optical devices in addition to semiconductors, MEMS, and LEDs. We applied vacuum technology and plasma technology cultivated in optical thin-film deposition equipment field to etching technology and completed dry etching equipment for new optical devices. The new equipment enables efficient and uniform heating and cooling of the entire substrate during etching, thereby improving productivity and expanding the range of applications for etching. In addition, it has addressed the problem of waste liquid discharged by conventional wet etching equipment.

The newly commercialized equipment has expanded our product lineup in addition to optical thin-film deposition equipment and enabled us to meet a wide range of advanced film deposition needs. It's use is mainly for smartphones, notebook computers, automotive and other touch panels, as well as cover glass for displays, and is capable of handling up to a 5.5-generation (1300 mm x 1,500 mm) glass substrate in terms of size. In the future, we also plan to complete etching systems for LED and RF filter devices.

Oporun will continue to accelerate R&D and expand the scope of its business as a comprehensive deposition equipment manufacturer applying optical thin film and semiconductor-related technologies. Furthermore, as part of our responsibility to realize a sustainable society, we will continue to work on developing eco-friendly products.

※Dry etching is an etching process in which reactive gas is introduced into a vacuum chamber to produce a plasma.

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